ICT Applications in Library Services Unit 4 Smart Card-Steps to construct a Smart Card

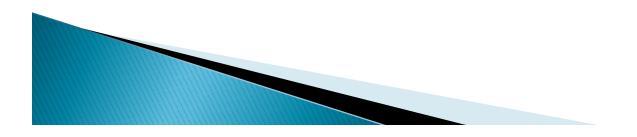




Steps to construct a Smart Card

<u>Designing</u>-

The designing involves specifying the chip for the memory size, speed, volatile memory types, types of operating system and specifying the application software, specifying the card type, size and functioning and additional features.



Chip Fabrication-

- This involves mounting the silicon chip on an epoxy glass substrate with gold plated connectors, using a die.
- The silicon chip is bonded to the connectors using connecting wires (wire bonding technique) or using flip chip technology (using a solder).



- The chip on board substrate is then sealed using glued to the card substrate. The card substrate can be PVC based plastic card or polyester based card.
- Loading of codes loading of code to the memory using special commands.
- Data loading Data loading into the POM memory such that the data pertains to a single

on.



